

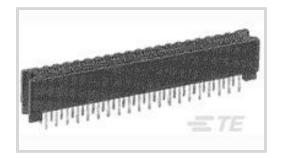
AMPMODU | Modu Connector System

TE Internal #: 5-534972-3 PCB Mount Receptacle, Vertical, Board-to-Board, 50 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **50**

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Sealable

PCB Mount Receptacle

Board-to-Board

No

Connector &	& Contact	Terminates To
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Printed Circuit Board

Configuration Features

Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	50
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Termination Resistance	12 mΩ
Dielectric Withstanding Voltage (Max)	750 VAC
Insulation Resistance	5000 MΩ
Operating Voltage	250 VAC
Body Features	
Primary Product Color	Black
Contact Features	

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Mating Square Post Dimension	.64 mm[.025 in]
	50 µin
Contact Layout	Inline
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Type	Socket
Contact Current Rating (Max)	3 A
Termination Features	
Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Rectangular Termination Post & Tail Width	.69 mm[.027 in]
Termination Post & Tail Length	2.92 mm[.115 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Retention	Without
Mating Alignment	With
Mating Alignment Type	Guide Pin Slots

Mating Alignment Type	Guide Pin Slots
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Mating Entry Location	Bottom & Top
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Philips Ryton
Dimensions	
	.238 in
Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	11.43 mm[.45 in]
PCB Thickness (Recommended)	1.4 mm[.055 in]
Usage Conditions	
Housing Temperature Rating	High

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Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Approved Standards	CSA LE7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Type	Tube
Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2027 (211)

(211) Does not contain REACH SVHC

Not Yet Reviewed for halogen content

Pin-in-Paste capable to 260°C

Halogen Content

Solder Process Capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

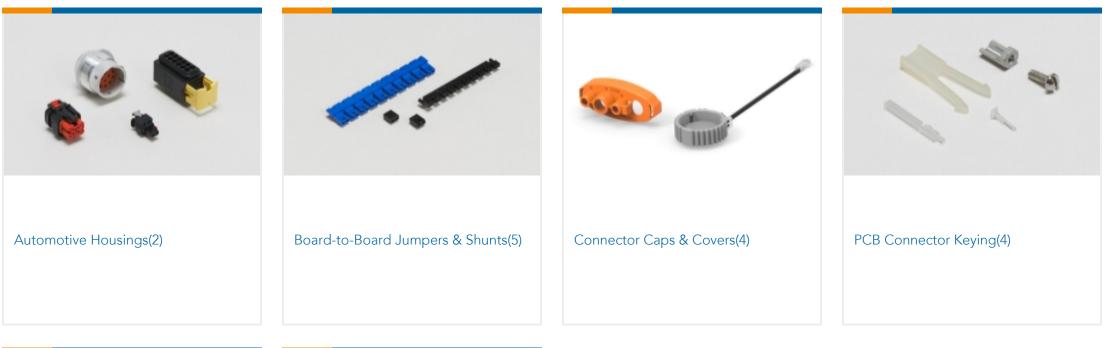
Compatible Parts

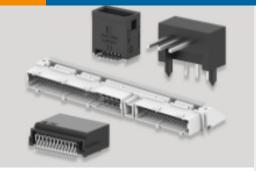
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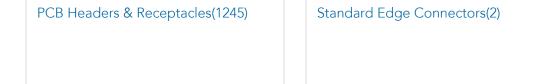


Also in the Series | Modu Connector System

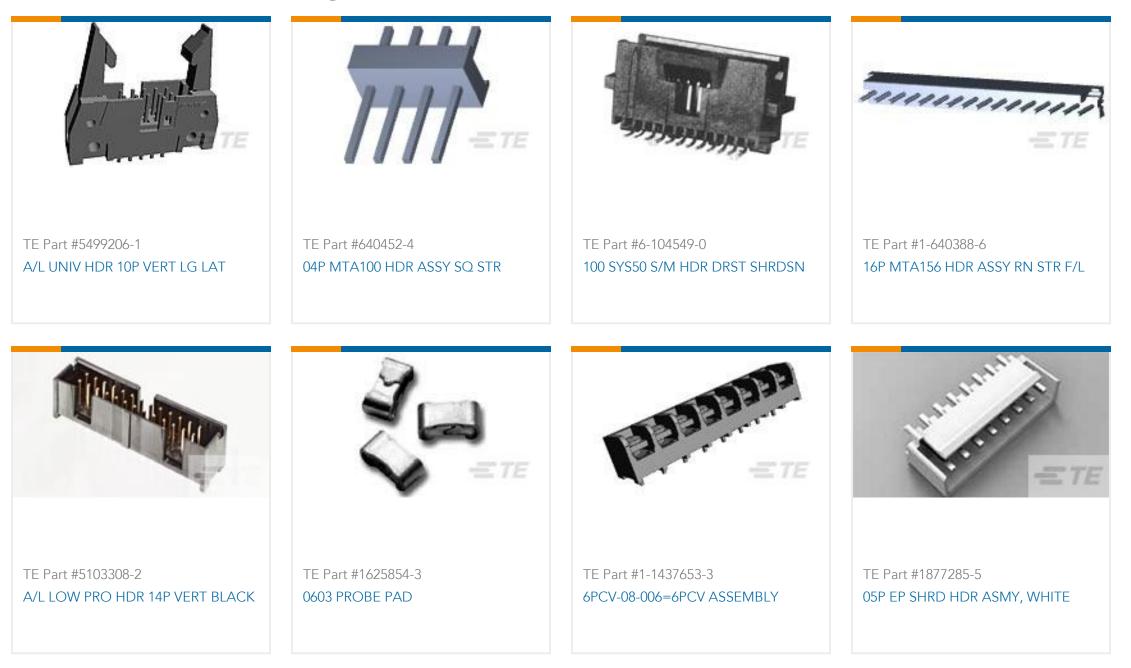








Customers Also Bought



PCB Mount Receptacle, Vertical, Board-to-Board, 50 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System



Documents

Product Drawings 50 MODII VRT 2PC DR CE 100CL, RoHS

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_5-534972-3_P1.3d_igs.zip

English

Customer View Model

ENG_CVM_5-534972-3_P1.3d_stp.zip

English

Customer View Model

ENG_CVM_5-534972-3_P1.2d_dxf.zip

English

3D PDF

English

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Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5_CONT

English